

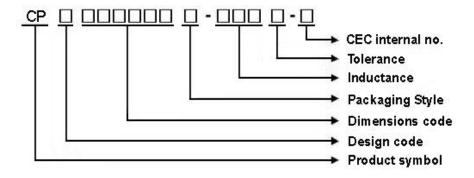
RoHS & Halogen Free & REACH Compliance.

SPECIFICATION FOR APPROVAL

Customer:						
Customer P/N:						
Drawing No:						
Quantity:	1 P	cs.	Date :	2025/03/10		
Pulse Series :		СР	Y201212T	-100T-N		
		_	ATION D BY:			
COMPONENT ENGINEER						
ELECTRICAL ENGINEER						
MECHANICAL ENGINEER						
APPROVED						
REJECTED						
				Yuliangwei Administration Area, guan City, Guangdong,China 3-0251~3		
No 143 - 145, Road No 10, VS Lap Le Commune, Thuy Nguye Haiphong City, Vietnam	Tel: 84-316 255 688 Fax: 84-316 255 Tel: 86-745-867-5882					
Applied by Huehue.Tran				Approved by Shuihua.Yu		



- 1 Scope: This specification applies to Multilayer Ferrite chip inductors
- 2 Part Numbering:



3 Rating:

Operating Temperature: -40 °C ~ 10 5 °C(Including self - temperature rise)

Storage Temperature: - 4 0 °C ~ 8 5 °C(after PCB)

- 5 °C~ 4 0 °C, Humidity 4 0 %~ 7 0 % (before PCB)

4 Marking:

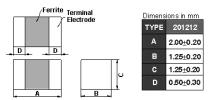
No Marking

5 Standard Testing Condition

	Unless otherwise specified	In case of doubt
Temperature	Ordinary Temperature(15 to 35°C)	20 to 30°C
Humidity	Ordinary Humidity(25 to 85% RH)	50 to 80 %RH



6 Configuration and Dimensions:



Net Weight (grms)	
Size Code	Net Weight (grms)
201212	0.01781

7 Electrical Characteristics:

Part No.	Inductance (uH)	Test Freq.	RDC (Ω)Max.	Rated Current (mA)Max.	Tolerance (±%)	
CPY201212T-100□-N	10	1 MHz,200 mV	0.5	150	20,30	

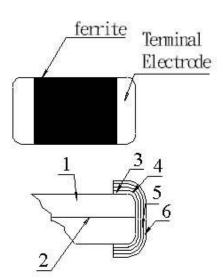
NOTE: □-tolerance M=±20% / T=±30%

1. Operating temperature range - 4 0 $^{\circ}$ C ~ 1 0 5 $^{\circ}$ C(Including self - temperature rise)

2.Rate Current : Applied the current to coils, the temperature rise shall not be more than 30°C



8 CPY201212T Series 8.1 Construction:



8.2 Material List:

No	Part	Material
1	Ferrite Substance	NiO-CuO-ZnO-Ferrite
2	Silver electrode	Ag
3	Silver electrode	Ag
4	Cu plating	Cu
5	Ni plating	Ni
6	Sn plating	Sn

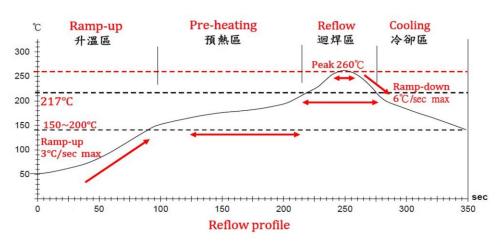


9 Reliability Of Ferrite Multilayer Chip Inductor 1-1.Mechanical Performance

No	ltem	Specification	Test Method
1-1-1	Flexure Strength	The forces applied on the right	Test device shall be soldered on the substrate
		conditions must not damage	Substrate Dimension: 100x40x1.6mm
		the terminal electrode and the	4
		ferrite	Keeping Time: 30sec
			*For 100505, substrate dimension is 100x40x0.8mm
1-1-2	Vibration		Test device shall be soldered on the substrate
			Oscillation Frequency: 10 to 55 to 10Hz for 1min
			Amplitude: 1.5mm
			Time: 2hrs for each axis (X, Y & Z), total 6hrs
1-1-3	Resistance to Soldering Heat	Appearance: No damage	Pre-heating: 150°C, 1min
		More than 75% of the terminal	Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free)
		electrode should be covered	Solder Temperature: 260±5°C
		with solder.	Immersion Time: 10±1sec
		Inductance: within ±20% of	
		initial value	
1-1-4	Solder ability	The electrodes shall be at	Pre-heating: 150°ℂ, 1min
	-	least 95% covered with new	Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free)
		solder coating	Solder Temperature: 245±5°C (Pb-Free)
			Immersion Time: 4±1sec

No	ltem	Specification		Test Method		
1-2-1	Temperature Cycle	Appearance: No damage	One cycle:			
		Inductance:within±20% of	Step	Temperature (°ℂ)	Time (min)	
		initial value	1	-40±3	30	
			2	25±2	3	
			3	105±3	30	
			4	25±2	3	
			Total: 100cycles Measured after exposure in the room condition			
1-2-2 Humidity Resistance Temperature: 4				re: 40±2℃		
			Relative Humidity: 90 ~ 95% / Time: 1000hrs			
			Measured after exposure in the room condi			
1-2-3	High		Temperature: 85±3°ℂ			
	Temperature Resistance		Relative H	umidity: 20%		
			Applied Current: Rated Current / Time: 1000hrs			
			Measured after exposure in the room condition for 24hr			
1-2-4	Low		Temperature: -40±3°C			
	Temperature Resistance		Relative H	umidity: 0% / Time: 1000hrs		
			Measured	after exposure in the room con	dition for 24hrs	





Lead-Free(LF)標準溫度分析範圍

Refer to J-STD-020C

管制項目 Item.	升溫區 Ramp-up	預熱區 Pre-heating	迴焊區 Reflow	Peak Temp	冷卻區 Cooling
溫度範圍 Temp.scope	R.T ~ 150℃	150°C ~ 200°C	Above 217°C	260±5℃	Peak Temp.~150°C
標準時間 Time spec.	-	60 ~ 180 sec	60 ~ 150 sec	20 ~ 40 sec	-
實際時間 Time result	_	75 ~ 100 sec	90 ~ 120 sec	20 ~ 35 sec	-

NOTE:

- 1. Re-flow possible times: within 2 times
- 2. Nitrogen adopted is recommended while in re-flow
- 3. Products can only be soldered with reflow



11 Packaging:

11.1 Packaging -Cover Tape

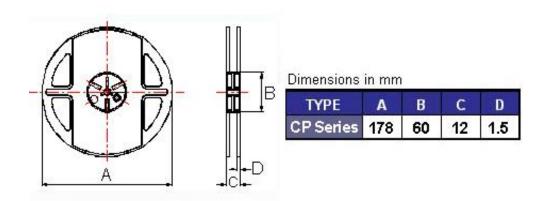
The force for tearing off cover tape is 10 to 100 grams in the arrow direction.



11.2 Packaging Quantity

TYPE	PCS/REEL
CP160808	4000
CP201209	4000
CP201212	3000
CP 32 1611	3000

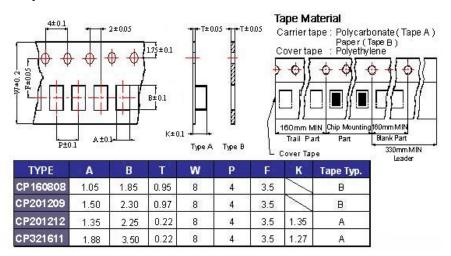
11.3 Reel Dimensions



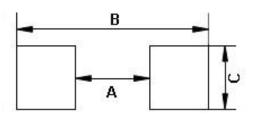


11 Packaging:

11.4 Tape Dimensions in mm



12 Recommended Land Pattern:



Dimensions in mm

TYPE A		В	С
CP160808	0.7 ~ 0.8	1.8 ~ 2.0	0.6 ~ 0.8
CP201209	1.0 ~ 1.2	2.6 ~4.0	1.0~1.2
CP201212	1.0 ~ 1.2	2.6 ~4.0	1.0~1.2

13 Note:

- 1. Please make sure that your product has been evaluated and confirmed against your specifications when our product is mounted to your product.
- 2. Do not knock nor drop.
- 3. All the items and parameters in this product specification have been prescribed on the premise that our product is used for the purpose,under the condition and in the environment agreed upon between you and us. You are requested not to use our product deviating from such agreement.
- 4. Please keep the distance between transformer/coil and other components (refer to the standard IEC 950)
- 5. The moisture sensitivity level (MSL) of products is classified as level 1.



14 Graph: CPY201212T-100T-N

